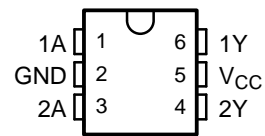


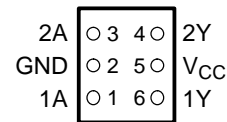
FEATURES

- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 5.4 ns at 3.3 V
- Low Power Consumption, 10-μA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} Feature Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE
(TOP VIEW)



YEA, YEP, YZA, OR YZP PACKAGE
(BOTTOM VIEW)



DESCRIPTION/ORDERING INFORMATION

This dual Schmitt-trigger inverter is designed for 1.65-V to 5.5-V V_{CC} operation.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING ⁽²⁾
–40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA	Reel of 3000	SN74LVC2G14YEAR	_ _ _ CF _
	NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free)		SN74LVC2G14YZAR	
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP		SN74LVC2G14YEPR	
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		SN74LVC2G14YZPR	
	SOT (SOT-23) – DBV	Reel of 3000	SN74LVC2G14DBVR	C14_
		Reel of 250	SN74LVC2G14DBVT	
	SOT (SC-70) – DCK	Reel of 3000	SN74LVC2G14DCKR	CF_
		Reel of 250	SN74LVC2G14DCKT	

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (2) DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.
 YEA/YZA, YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar, NanoFree are trademarks of Texas Instruments.

SN74LVC2G14 DUAL SCHMITT-TRIGGER INVERTER

SCES200J—APRIL 1999—REVISED JUNE 2005

DESCRIPTION/ORDERING INFORMATION (CONTINUED)

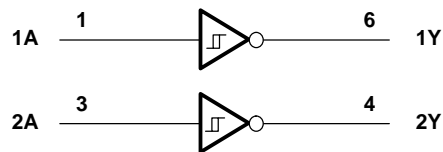
The SN74LVC2G14 contains two inverters and performs the Boolean function $Y = \bar{A}$. The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

**FUNCTION TABLE
(EACH INVERTER)**

INPUT A	OUTPUT Y
H	L
L	H

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	6.5	V
V_I	Input voltage range ⁽²⁾	-0.5	6.5	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	6.5	V
V_O	Voltage range applied to any output in the high or low state ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$	-50	mA
I_{OK}	Output clamp current	$V_O < 0$	-50	mA
I_O	Continuous output current		± 50	mA
	Continuous current through V_{CC} or GND		± 100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DBV package	165	°C/W
		DCK package	259	
		YEA/YZA package	143	
		YEP/YZP package	123	
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) The value of V_{CC} is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT	
V_{CC}	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V_I	Input voltage	0	5.5	V	
V_O	Output voltage	0	V_{CC}	V	
I_{OH}	High-level output current	$V_{CC} = 1.65\text{ V}$		–4	mA
		$V_{CC} = 2.3\text{ V}$		–8	
		$V_{CC} = 3\text{ V}$		–16	
		$V_{CC} = 4.5\text{ V}$		–24	
I_{OL}	Low-level output current	$V_{CC} = 1.65\text{ V}$		4	mA
		$V_{CC} = 2.3\text{ V}$		8	
		$V_{CC} = 3\text{ V}$		16	
		$V_{CC} = 4.5\text{ V}$		24	
T_A	Operating free-air temperature	–40	85	°C	

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74LVC2G14

DUAL SCHMITT-TRIGGER INVERTER

SCES200J–APRIL 1999–REVISED JUNE 2005

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{T+} Positive-going input threshold voltage			1.65 V	0.7		1.4	V
			2.3 V	1		1.7	
			3 V	1.3		2.2	
			4.5 V	1.9		3.1	
			5.5 V	2.2		3.7	
V _{T-} Negative-going input threshold voltage			1.65 V	0.3		0.7	V
			2.3 V	0.4		1	
			3 V	0.6		1.3	
			4.5 V	1.1		2	
			5.5 V	1.4		2.5	
ΔV _T Hysteresis (V _{T+} – V _{T-})			1.65 V	0.3		0.8	V
			2.3 V	0.4		0.9	
			3 V	0.4		1.1	
			4.5 V	0.6		1.3	
			5.5 V	0.7		1.4	
V _{OH}		I _{OH} = –100 μA	1.65 V to 4.5 V	V _{CC} – 0.1			V
		I _{OH} = –4 mA	1.65 V	1.2			
		I _{OH} = –8 mA	2.3 V	1.9			
		I _{OH} = –16 mA	3 V	2.4			
		I _{OH} = –24 mA	3 V	2.3			
		I _{OH} = –32 mA	4.5 V	3.8			
V _{OL}		I _{OL} = 100 μA	1.65 V to 4.5 V			0.1	V
		I _{OL} = 4 mA	1.65 V			0.45	
		I _{OL} = 8 mA	2.3 V			0.3	
		I _{OL} = 16 mA	3 V			0.4	
		I _{OL} = 24 mA	3 V			0.55	
		I _{OL} = 32 mA	4.5 V			0.55	
I _I	A input	V _I = 5.5 V or GND	0 to 5.5 V			±5	μA
I _{off}		V _I or V _O = 5.5 V	0			±10	μA
I _{CC}		V _I = 5.5 V or GND, I _O = 0	1.65 V to 5.5 V			10	μA
ΔI _{CC}		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 5.5 V			500	μA
C _i		V _I = V _{CC} or GND	3.3 V			4	pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

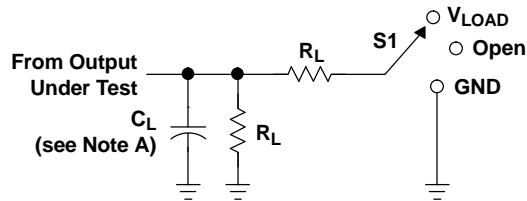
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	3.9	9.5	1.9	5.7	2	5.4	1.5	4.3	ns

Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	$V_{CC} = 5\text{ V}$	UNIT
		TYP	TYP	TYP	TYP	
C_{pd} Power dissipation capacitance	$f = 10\text{ MHz}$	16	17	18	21	pF

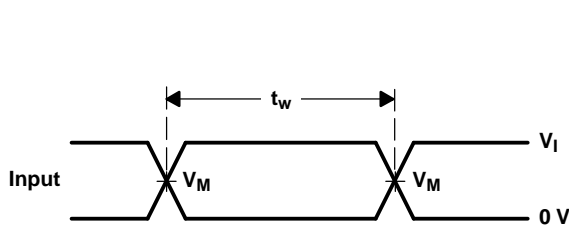
PARAMETER MEASUREMENT INFORMATION



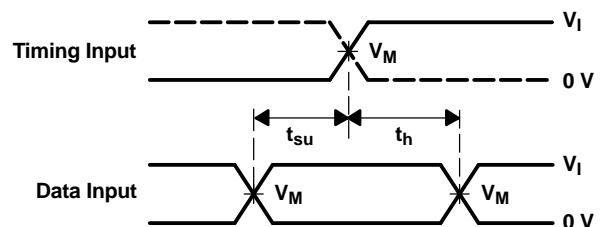
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

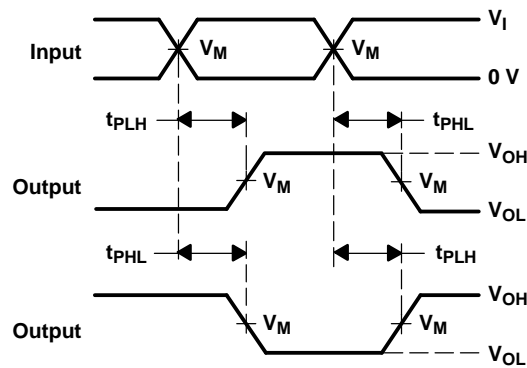
V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	V_{CC}	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 Ω	0.3 V



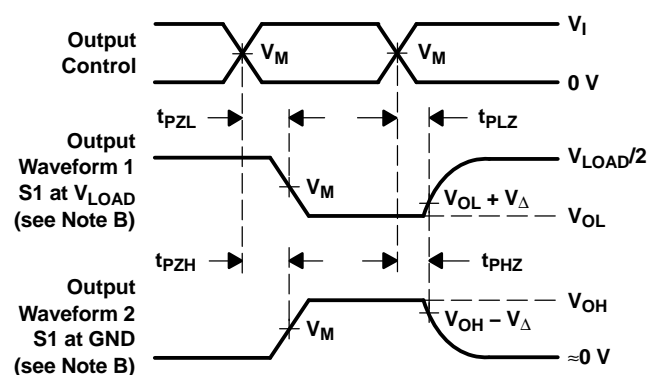
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC2G14DBVR	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC2G14DBVRG4	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC2G14DBVT	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC2G14DBVTE4	ACTIVE	SOT-23	DBV	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC2G14DCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC2G14DCKRE4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC2G14DCKRG4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC2G14DCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC2G14DCKTE4	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC2G14YEAR	ACTIVE	WCSP	YEA	6	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74LVC2G14YEPR	ACTIVE	WCSP	YEP	6	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74LVC2G14YZAR	ACTIVE	WCSP	YZA	6	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM
SN74LVC2G14YZPR	ACTIVE	WCSP	YZP	6	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

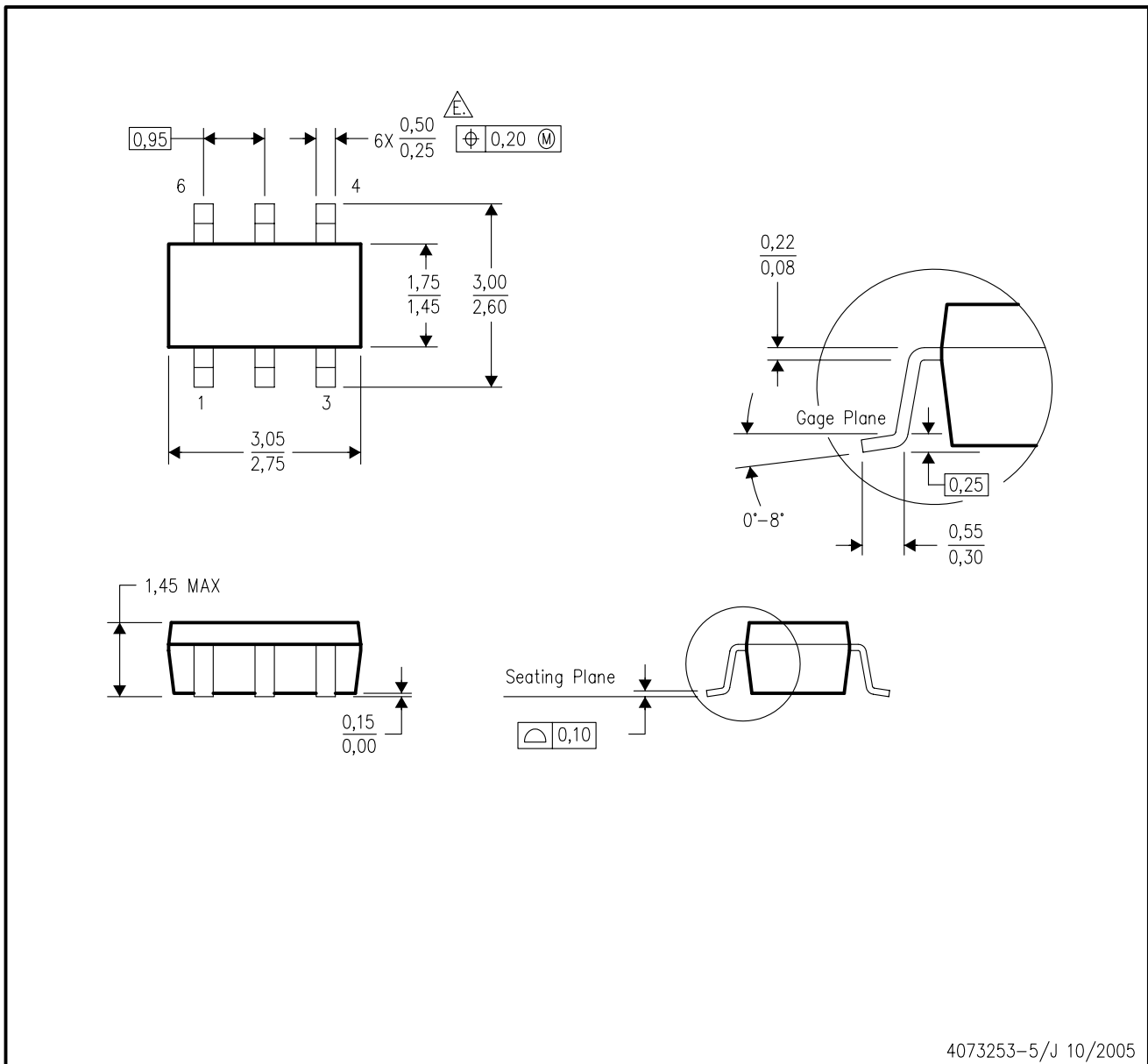
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DBV (R-PDSO-G6)

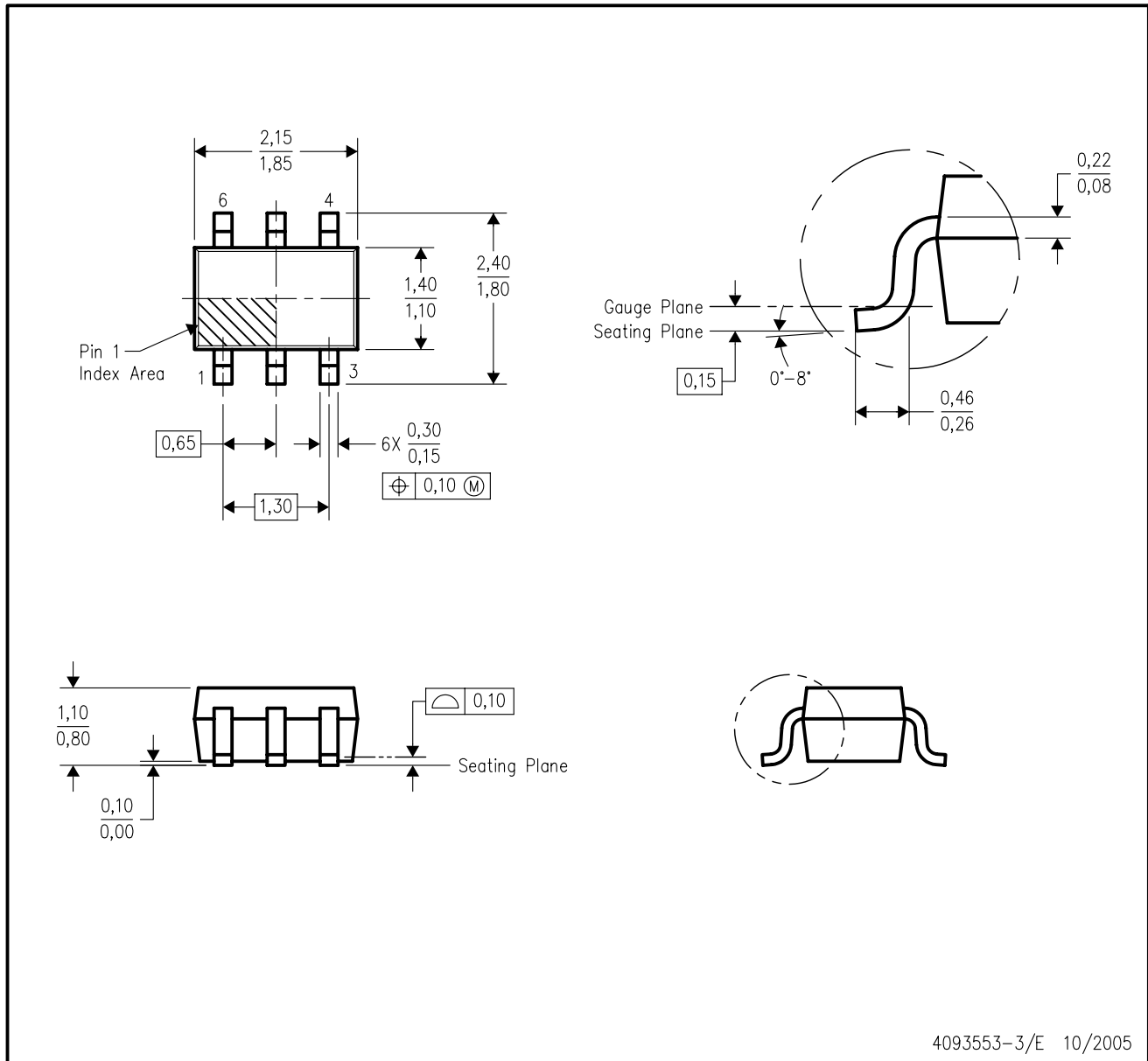
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- \triangle Falls within JEDEC MO-178 Variation AB, except minimum lead width.

DCK (R-PDSO-G6)

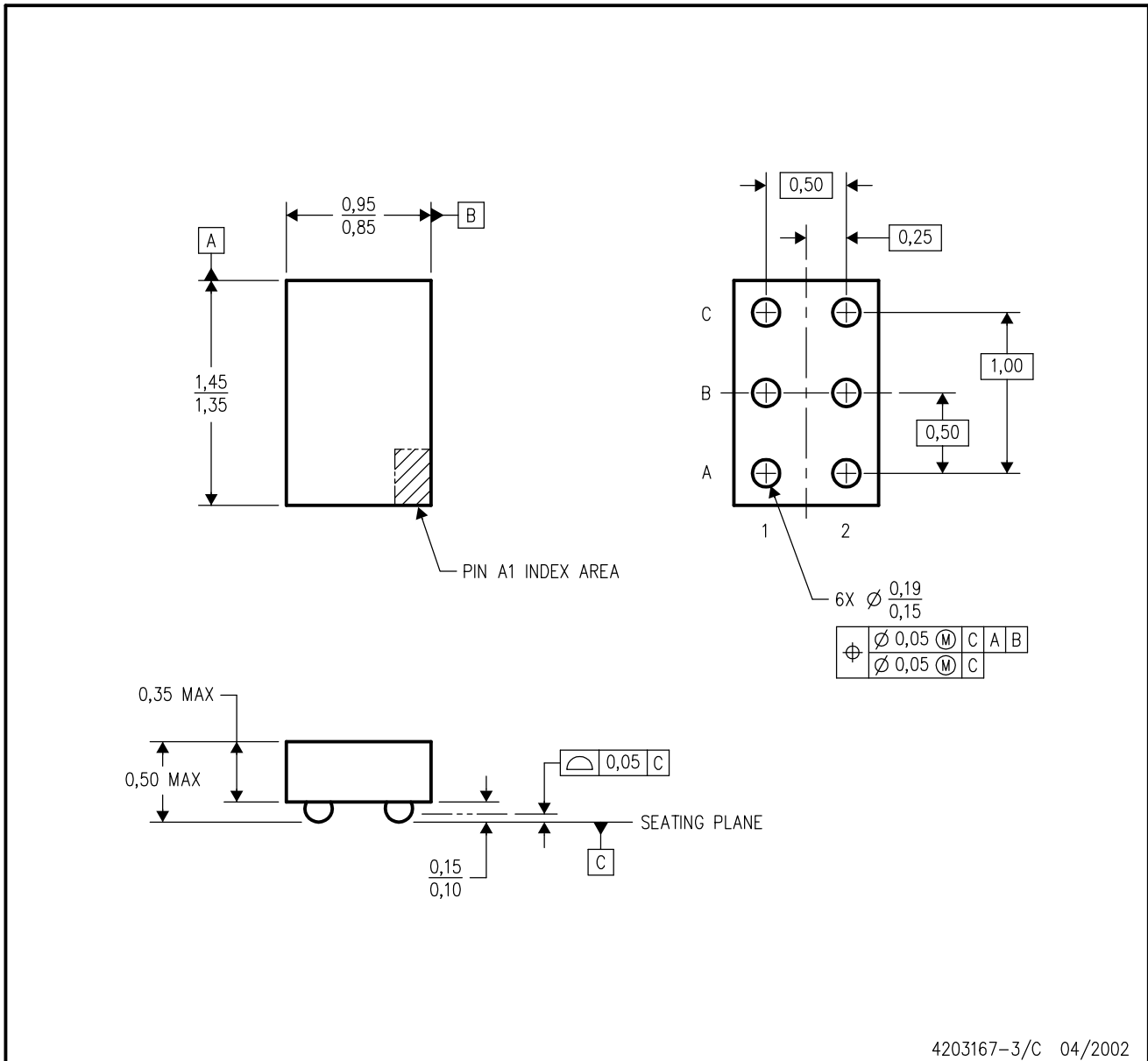
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AB.

YEA (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY

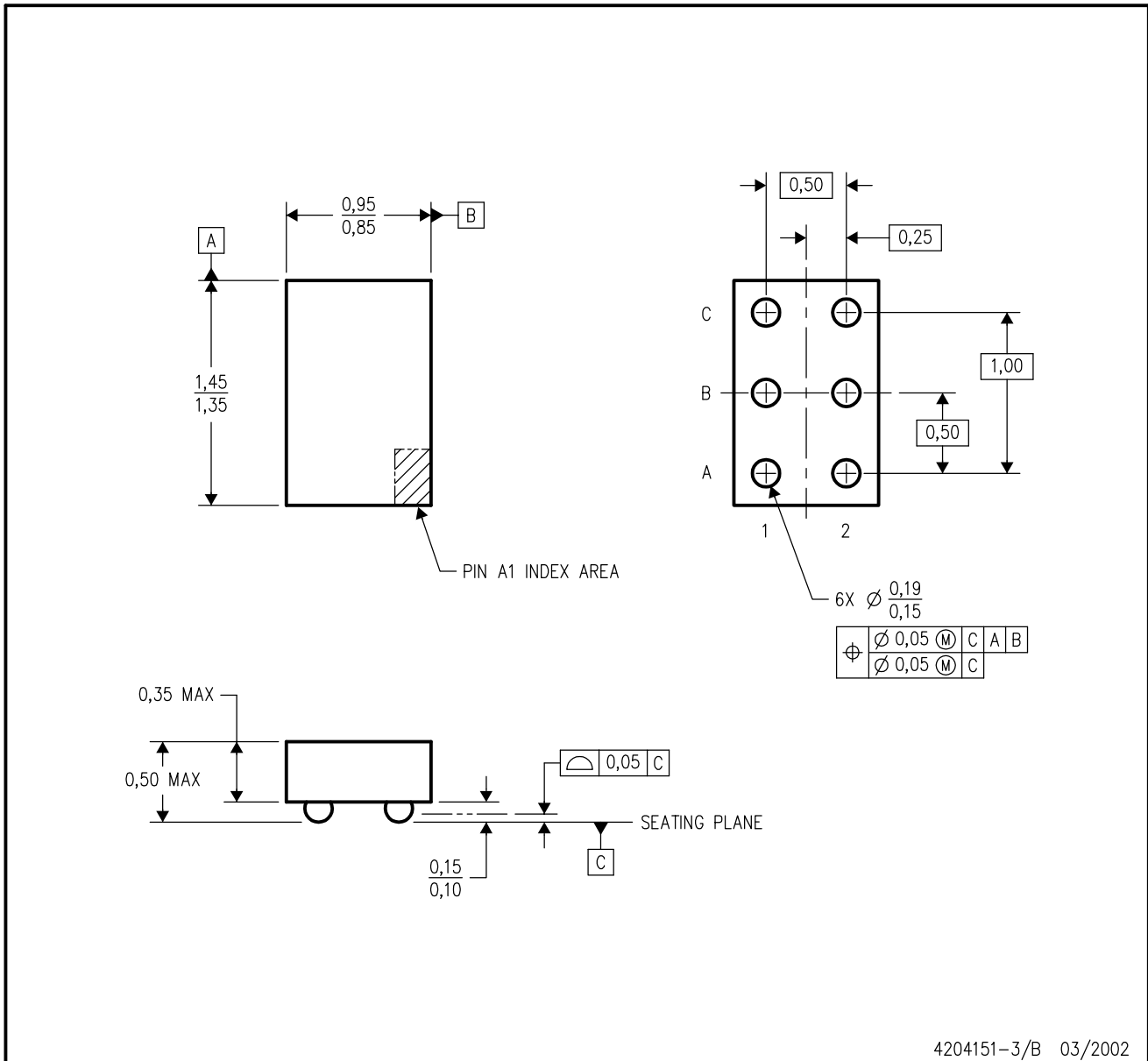


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoStar™ package configuration.
 - D. Package complies to JEDEC MO-211 variation EA.
 - E. This package is tin-lead (SnPb). Refer to the 6 YZA package (drawing 4204151) for lead-free.

NanoStar is a trademark of Texas Instruments.

YZA (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY

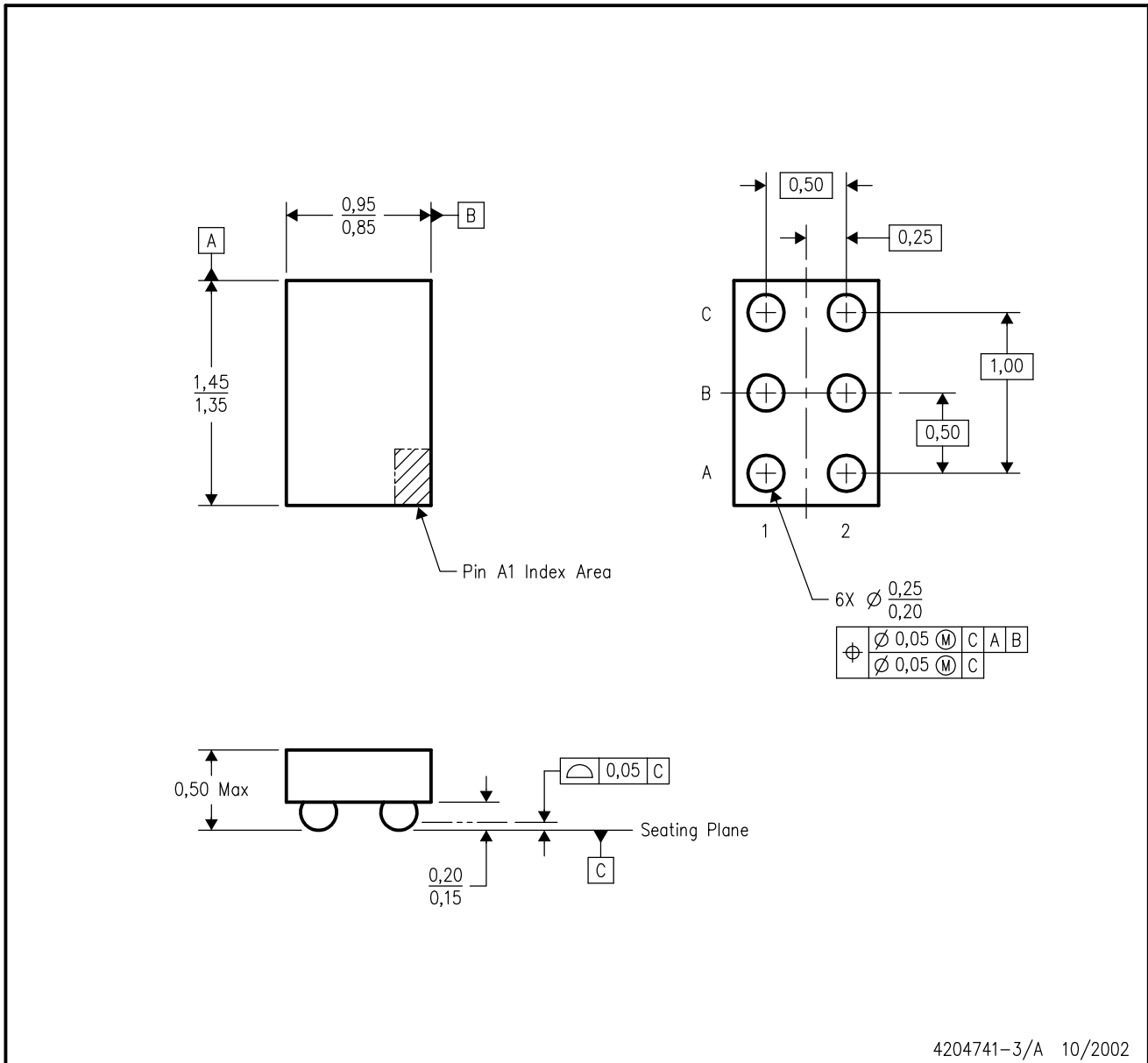


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - D. Package complies to JEDEC MO-211 variation EA.
 - E. This package is lead-free. Refer to the 6 YEA package (drawing 4203167) for tin-lead (SnPb).

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YZP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY

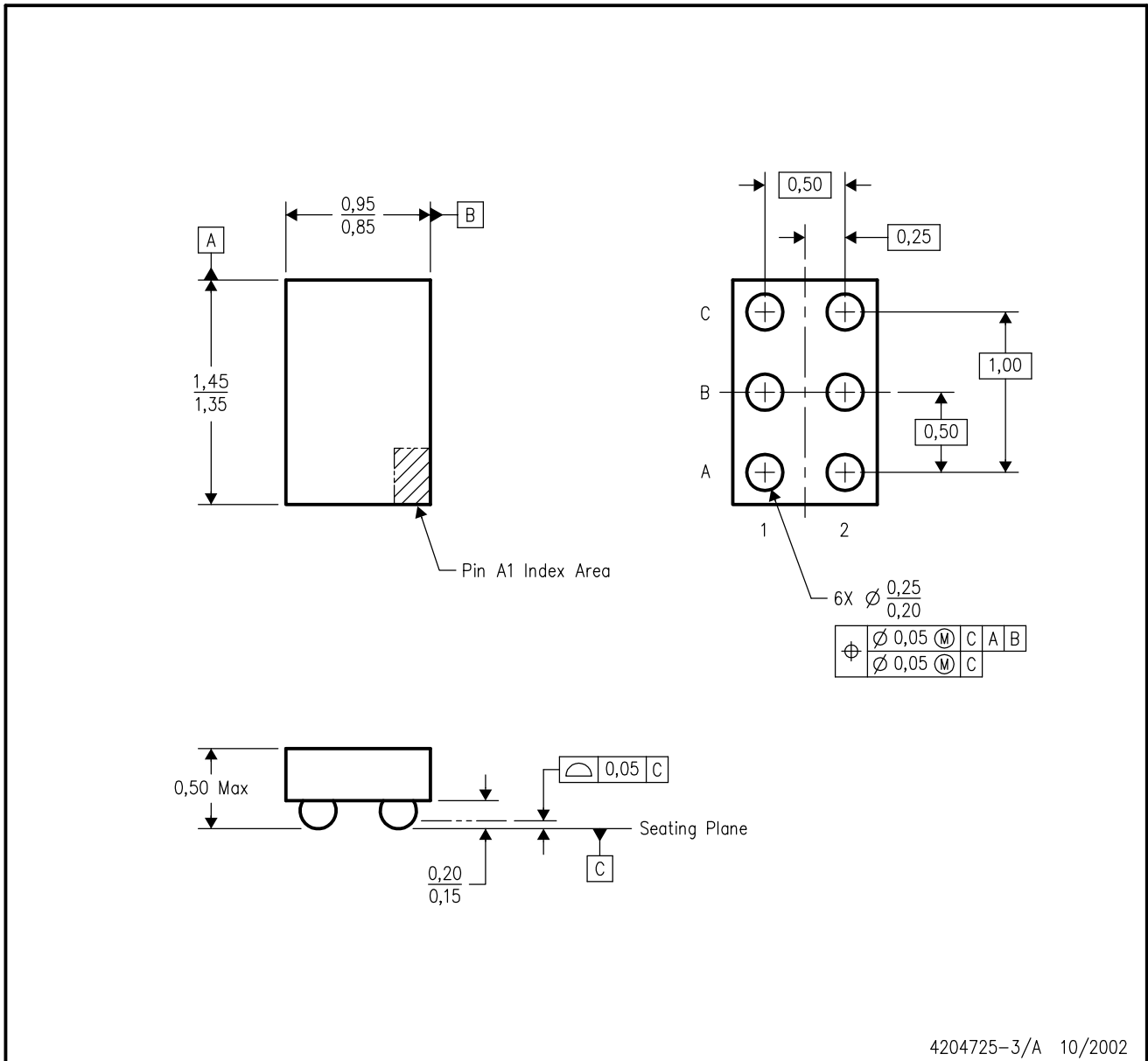


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - D. This package is lead-free. Refer to the 6 YEP package (drawing 4204725) for tin-lead (SnPb).

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YEP (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoStar™ package configuration.
 - D. This package is tin-lead (SnPb). Refer to the 6 YZP package (drawing 4204741) for lead-free.

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View ROHS Compliant Devices

View RoHS Compliant Devices

clear gif

SN74LVC2G14, Status: ACTIVE
Dual Schmitt-Trigger Inverter



clear gif

Features	Samples	Technical Documents
Quality & Pb-Free Data	Pricing/Packaging	Applications Notes
Related Products	Inventory	Simulation Models
Tools & Software	Symbols/Footprints	Reference Designs

Support

- KnowledgeBase
- Contact Technical Support
- TI Cross Reference
- Training
- Part Marking Lookup
- Part Number Nomenclature

Datasheet



Download Datasheet **SN74LVC2G14 (Rev. J)** (sn74lvc2g14.pdf, 386 KB)
11 Sep 2003 [Download](#)

	LVC2G14-1.8	LVC2G14-2.5	LVC2G14-3.3	LVC2G14-5.0
Voltage Node(V)	1.8	2.5	3.3	5
Performance			Optimized	
Vcc min(V)	1.65	1.65	1.65	1.65
Vcc max(V)	5.5	5.5	5.5	5.5
IOH(mA)	-4	-8	-24	-32
IOL(mA)	4	8	24	32
tpd max(ns)	9.5	5.7	5.4	4.3
ICC(uA)	10	10	10	10
Input Level	1.8V CMOS	2.5V CMOS	LV TTL	CMOS
Output Level	1.8V CMOS	2.5V CMOS	LV TTL	CMOS
No. of Gates	2	2	2	2
	Samples	Samples	Samples	Samples
	Inventory Not Available	Inventory Not Available	Inventory Not Available	Inventory Not Available

Product Information

Features [Save this to your personal library](#)

Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
 Supports 5-V V_{CC} Operation
 Inputs Accept Voltages to 5.5 V
 Max t_{pd} of 5.4 ns at 3.3 V
 Low Power Consumption, 10-µA Max I_{CC}
 @24-mA Output Drive at 3.3 V
 Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
 Typical V_{OHV} (Output V_{OH} Undershoot)
 >2 V at V_{CC} = 3.3 V, T_A = 25°C
 I_{off} Supports Partial-Power-Down Mode Operation
 Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
 ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)

NanoStar and NanoFree are trademarks of Texas Instruments.

Description

This dual Schmitt-trigger inverter is designed for 1.65-V to 5.5-V V_{CC} operation.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

The SN74LVC2G14 contains two inverters and performs the Boolean function $Y = A\bar{A}$. The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

Pricing/Packaging/CAD Design Tools/Samples

			Price	Packaging			CAD Design Tools	Samples
Device	Status	Temp (°C)	Budget Price (\$US) QTY	Industry Standard (TI Pkg) Pins	Top Side Marking	Standard Pack Quantity	Footprints	Samples
SN74LVC2G14DBVR	ACTIVE	-40 to 85	0.12 1KU	SOT-23 (DBV) 6	View	3000	<input type="checkbox"/>	Request Free Samples
SN74LVC2G14DBVRG4	ACTIVE	-40 to 85	0.14 1KU	SOT-23 (DBV) 6	View	3000	<input type="checkbox"/>	Purchase Samples
SN74LVC2G14DBVT	ACTIVE	-40 to 85	0.35 1KU	SOT-23 (DBV) 6	View	250	<input type="checkbox"/>	Purchase Samples
SN74LVC2G14DBVTE4	ACTIVE	-40 to 85	0.35 1KU	SOT-23 (DBV) 6	View	250	<input type="checkbox"/>	Purchase Samples
SN74LVC2G14DCKR	ACTIVE	-40 to 85	0.12 1KU	SC70 (DCK) 6	View	3000	<input type="checkbox"/>	Request Free Samples
SN74LVC2G14DCKRE4	ACTIVE	-40 to 85	0.12 1KU	SC70 (DCK) 6	View	3000	<input type="checkbox"/>	Request Free Samples
SN74LVC2G14DCKRG4	ACTIVE	-40 to 85	0.14 1KU	SC70 (DCK) 6	View	3000	<input type="checkbox"/>	Purchase Samples
SN74LVC2G14DCKT	ACTIVE	-40 to 85	0.35 1KU	SC70 (DCK) 6	View	250	<input type="checkbox"/>	Purchase Samples
SN74LVC2G14DCKTE4	ACTIVE	-40 to 85	0.35 1KU	SC70 (DCK) 6	View	250	<input type="checkbox"/>	Purchase Samples
SN74LVC2G14YEAR	ACTIVE	-40 to 85	0.21 1KU	WCSP (YEA) 6		3000	<input type="checkbox"/>	Request Free Samples
SN74LVC2G14YEPR	ACTIVE	-40 to 85	0.21 1KU	WCSP (YEP) 6		3000	<input type="checkbox"/>	Purchase Samples
SN74LVC2G14YZAR	ACTIVE	-40 to 85	0.21 1KU	WCSP (YZA) 6		3000	<input type="checkbox"/>	Purchase Samples
SN74LVC2G14YZPR	ACTIVE	-40 to 85	0.21 1KU	WCSP (YZP) 6		3000	<input type="checkbox"/>	Request Free Samples

Inventory

	TI Inventory Status			Reported Distributor Inventory			
SN74LVC2G14DBVR	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	>10k*	>10k 12 Dec	4 Weeks	Americas	DigiKey	>1k	<input type="text"/>
					Newark InOne	>1k	<input type="text"/>
				Europe	Avnet-SILICA	250	<input type="text"/>
SN74LVC2G14DBVRG4	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	0*	>10k 30 Dec	6 Weeks	None Reported View Distributors			
SN74LVC2G14DBVT	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	>10k*	>10k 3 Jan	6 Weeks	Europe	Abacus Polar	>1k	<input type="text"/>
					Spoerle	970	<input type="text"/>
SN74LVC2G14DBVTE4	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			

[View all Distributors](#)

Choose a Region



	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	>10k*	>10k 3 Jan	6 Weeks	None Reported View Distributors			
SN74LVC2G14DCKR	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	3825*	>10k 12 Dec	4 Weeks	Americas	DigiKey	>1k	<input type="text"/>
				Asia	P&S	174	<input type="text"/>
				Europe	Avnet-SILICA	>1k	<input type="text"/>
SN74LVC2G14DCKRE4	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	3825*	>10k 12 Dec	4 Weeks	None Reported View Distributors			
SN74LVC2G14DCKRG4	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	0*	>10k 12 Dec	6 Weeks	None Reported View Distributors			
SN74LVC2G14DCKT	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	0*	>10k 7 Feb	10 Weeks	Asia	P&S	250	<input type="text"/>
SN74LVC2G14DCKTE4	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	0*	>10k 7 Feb	10 Weeks	None Reported View Distributors			
SN74LVC2G14YEAR	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	0*	>10k 10 Jan	6 Weeks	Americas	DigiKey	>1k	<input type="text"/>
SN74LVC2G14YEPR	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	0*	>10k 12 Dec	6 Weeks	None Reported View Distributors			
SN74LVC2G14YZAR	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	0*	>10k 24 Jan	8 Weeks	None Reported View Distributors			
SN74LVC2G14YZPR	As of 9:06 AM GMT, 29 Nov 2005			As of 9:06 AM GMT, 29 Nov 2005			
	In Stock	In Progress QTY Date	Lead Time	Region	Company	In Stock	Purchase
	0*	>10k 12 Dec	6 Weeks	Americas	DigiKey	>1k	<input type="text"/>

* Our information is updated daily, so please check back with us soon if this does not meet your needs. You may also contact your [TI Authorized Distributor](#), including those [listed above](#), for real time stock information.

** Lead time information is not available at this time. However, our information is updated daily so please check back with us soon. Please contact your preferred [TI Authorized Distributor](#) for additional information.

Quality & Lead (Pb)-Free Data

	Product Content				MTBF/FIT Rate	
Device	Eco Plan*	Lead/Ball Finish	MSL Rating/Peak Reflow	Details	Details	
SN74LVC2G14DBVR <input type="checkbox"/>	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View	
SN74LVC2G14DBVRG4 <input type="checkbox"/>	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View	
SN74LVC2G14DBVT <input type="checkbox"/>	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View	
SN74LVC2G14DBVTE4 <input type="checkbox"/>	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View	
SN74LVC2G14DCKR <input type="checkbox"/>	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View	
SN74LVC2G14DCKRE4 <input type="checkbox"/>	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View	
SN74LVC2G14DCKRG4 <input type="checkbox"/>	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View	
SN74LVC2G14DCKT <input type="checkbox"/>	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View	
SN74LVC2G14DCKTE4 <input type="checkbox"/>	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	View	View	
SN74LVC2G14YEAR	TBD	SNPB	Level-1-260C-UNLIM	View	View	
SN74LVC2G14YEPR	TBD	SNPB	Level-1-260C-UNLIM	View	View	
SN74LVC2G14YZAR <input type="checkbox"/>	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM	View	View	
SN74LVC2G14YZPR <input type="checkbox"/>	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM	View	View	

* The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please click on the Product Content Details "View" link in the table above for the latest availability information and additional product content details.

If the information you are requesting is not available online at this time, contact one of our [Product Information Centers](#) regarding the availability of this information.

Technical Documents

Datasheets	Keep track of what's new
SN74LVC2G14 (Rev. J) (sn74lvc2g14.pdf, 386 KB) 11 Sep 2003 Download	
Application Notes	
Semiconductor Packing Material Electrostatic Discharge (ESD) Protection (szza047.htm, 9 KB) 08 Jul 2004 Abstract	
Selecting the Right Level Translation Solution (Rev. A) (scea035a.htm, 9 KB) 22 Jun 2004 Abstract	
Shelf-Life Evaluation of Lead-Free Component Finishes (szza046.htm, 9 KB) 24 May 2004 Abstract	
Use of the CMOS Unbuffered Inverter in Oscillator Circuits (szza043.htm, 9 KB) 06 Nov 2003 Abstract	
Understanding and Interpreting Standard-Logic Data Sheets (Rev. B) (szza036b.htm, 8 KB) 28 May 2003 Abstract	
Texas Instruments Little Logic Application Report (scea029.htm, 9 KB) 01 Nov 2002 Abstract	
TI IBIS File Creation, Validation, and Distribution Processes (szza034.htm, 9 KB) 29 Aug 2002 Abstract	
16-Bit Widebus Logic Families in 56-Ball, 0.65-mm Pitch Very Thin Fine-Pitch BGA (Rev. B) (szza029b.htm, 9 KB) 22 May 2002 Abstract	
Power-Up 3-State (PU3S) Circuits in TI Standard Logic Devices (szza033.htm, 9 KB) 10 May 2002 Abstract	
Selecting the Right Texas Instruments Signal Switch (szza030.htm, 9 KB) 07 Sep 2001 Abstract	
Implications of Slow or Floating CMOS Inputs (Rev. C) (scba004c.htm, 9 KB) 01 Feb 1998 Abstract	
Bus-Interface Devices With Output-Damping Resistors Or Reduced-Drive Outputs (Rev. A) (scba012a.htm, 9 KB) 01 Aug 1997 Abstract	
CMOS Power Consumption and CPD Calculation (Rev. B) (scaa035b.htm, 9 KB) 01 Jun 1997 Abstract	
LVC Characterization Information (scba011.htm, 9 KB) 01 Dec 1996 Abstract	
Live Insertion (sdya012.htm, 9 KB) 01 Oct 1996 Abstract	
Input and Output Characteristics of Digital Integrated Circuits (sdya010.htm, 9 KB) 01 Oct 1996 Abstract	

Understanding Advanced Bus-Interface Products Design Guide (scaa029.pdf, 253 KB)

01 May 1996 [Download](#)

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User Guides

Signal Switch Data Book (Rev. A) (scdd003a.pdf, 19732 KB)

14 Nov 2003 [Download](#)

LVC and LV Low-Voltage CMOS Logic Data Book (Rev. B) (scbd152b.pdf, 13291 KB)

18 Dec 2002 [Download](#)

LOGIC Pocket Data Book (scyd013.pdf, 4835 KB)

05 Dec 2002 [Download](#)

Simulation Models

IBIS Model

IBIS Model of SN74LVC2G14 (Rev. B) (scem252b.ibs, 247 KB)

18 Aug 2003 [ibis](#) / [zip](#)

More Literature

Logic Selection Guide 2005 (Rev. X) (sdyu001x.pdf, 6909 KB)

15 Mar 2005 [Download](#)

Wireless Infrastructure Solutions Guide (2Q2005) (Rev. E) (sstc001e.pdf, 734 KB)

14 Jan 2005 [Download](#)

Design Summary for WCSP Little Logic (Rev. B) (scet007b.pdf, 295 KB)

04 Nov 2004 [Download](#)

Dual- Supply Translation Product Clip (scyb033.pdf, 230 KB)

07 Sep 2004 [Download](#)

Military Semiconductors Selection Guide 2004-2005 (Rev. D) (sgyc003d.pdf, 964 KB)

10 Aug 2004 [Download](#)

SN74LVC1G97 and SN74LVC1G98 Product Clip (Rev. A) (scyb010a.pdf, 253 KB)

13 Jul 2004 [Download](#)

Logic Cross-Reference (Rev. A) (scyb017a.pdf, 2938 KB)

07 Oct 2003 [Download](#)

SN74LVC1G3157 and SNS74LVC2G53 SPDT Analog Switches (scyb014.pdf, 65 KB)

12 Jun 2003 [Download](#)

Standard Linear & Logic for PCs, Servers & Motherboards (scyb005.pdf, 3997 KB)

13 Jun 2002 [Download](#)

STANDARD LINEAR AND LOGIC FOR DVD/VCD PLAYERS (scym001.pdf, 5872 KB)

27 Mar 2002 [Download](#)

Military Low Voltage Solutions (sgyn139.pdf, 103 KB)

04 Apr 2001 [Download](#)

Low-Voltage Logic (LVC) Designer's Guide (scba010.htm, 9 KB)

01 Sep 1996 [Abstract](#)

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Tools & Software

<input type="checkbox"/> Name	Part #	Company	Software/Tool Type
TAS5001-5122C2EVM Evaluation Module	TAS5001-5122C2EVM	Texas Instruments	Development Boards/EVMs



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